

ABSTRACT OF THE DISCLOSURE

The present disclosure relates to a probe card for testing semiconductor chips on a semiconductor wafer comprising: a circuit board receiving electrical signals from outside; a plurality of unit probe modules contacting the semiconductor chips on the wafer to transfer the electrical signals; a space transformer having the plurality of probe modules seated on the upper portion thereof and electrically connected to the circuit board, wherein the respective probe modules are arranged at intervals from each other on the space transformer and the space transformer has vertical apertures penetrating through it up and down; and at least one vertical conductive medium electrically connecting the respective unit probe modules and the circuit board, wherein the vertical conductive medium is arranged in the vertical apertures provided in the space transformer and the respective unit probe modules are arranged at positions spaced from the vertical conductive medium.

Fig. 3